MP7542

5 V CMOS
4-Bit Input, 12-Bit
Digital-to-Analog Converter

FEATURES

- **12-Bit DAC with a 4-Bit Parallel Address for 4 & 8-Bit Microprocessor or Microcontroller Interface**
- **Nonlinearity ±1/2 LSB Tmin to Tmax**
- **Latch-Up Free**
- **Low Sensitivity to Output Amplifier V_{OS}**
- **Low Output Capacitance**
- **+5 V Supply Operation**
- **Low Power Consumption: 40mW Max.**
- **Low Cost**
- **Serial Version: MP7543**

GENERAL DESCRIPTION

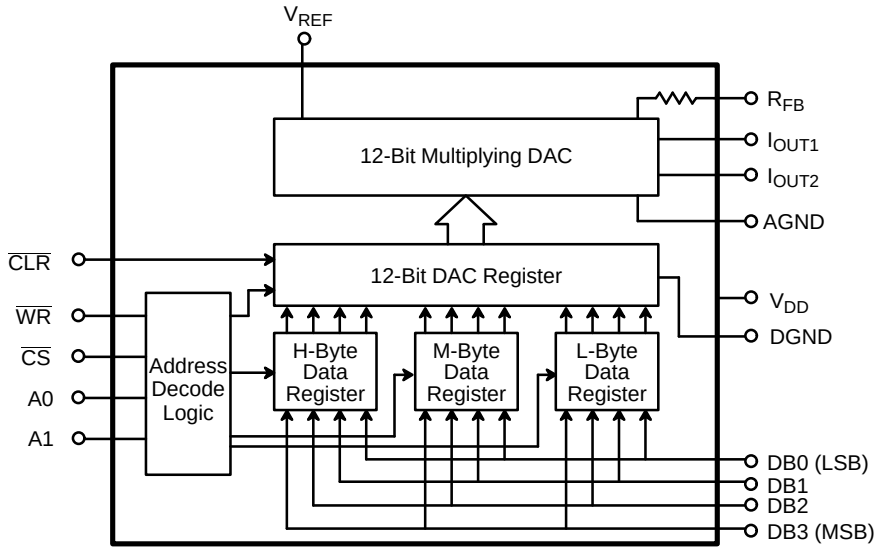
The MP7542 is a precision, 12-bit CMOS 4-quadrant multiplying Digital-to-Analog Converter designed for direct interface to 4 and 8-bit microprocessors.

The MP7542 consists of three 4-bit registers, a 12-bit DAC register, address decoding logic, and a 12-bit CMOS multiplying DAC. Data is loaded into the data registers in three 4-bit nibbles and subsequently transferred to the 12-bit DAC register. All data loading or data transfer operations are identical to the WRITE cycle of a static RAM. A CLEAR input allows the 12-bit DAC register to be reset to all zeros.

The MP7542 is manufactured using advanced thin-film on monolithic double metal CMOS fabrication process. A unique decoding technique is utilized yielding excellent accuracy and stability.

The MP7542 reduces the additional linearity errors due to output amplifier offset to only 330µV per millivolt of offset versus 670 µV for the standard R-2R ladder CMOS DACs.

SIMPLIFIED BLOCK DIAGRAM



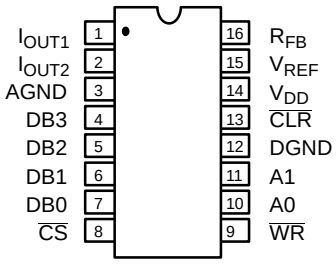
ORDERING INFORMATION

Package Type	Temperature Range	Part No.	INL (LSB)	DNL (LSB)	Gain Error (LSB)
Plastic Dip	–40 to +85°C	MP7542JN	±1	±2	±14.5
Plastic Dip	–40 to +85°C	MP7542KN	±1/2	±1	±14.5
SOIC	–40 to +85°C	MP7542JS	±1	±2	±14.5
SOIC	–40 to +85°C	MP7542KS	±1/2	±1	±14.5
Ceramic Dip	–40 to +85°C	MP7542AD	±1	±2	±14.5
Ceramic Dip	–40 to +85°C	MP7542BD	±1/2	±1	±14.5
Ceramic Dip	–55 to +125°C	MP7542SD*	±1	±2	±14.5
Ceramic Dip	–55 to +125°C	MP7542TD*	±1/2	±1	±14.5

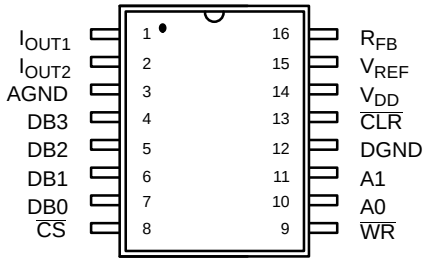
*Contact factory for non-compliant military processing

PIN CONFIGURATIONS

See Packaging Section for Package Dimensions



16 Pin CDIP, PDIP (0.300")
D16, N16



16 Pin SOIC (Jedec, 0.300")
S16

PIN OUT DEFINITIONS

PIN NO.	NAME	DESCRIPTION
1	I_{OUT1}	DAC current output. Normally terminated at op amp.
2	I_{OUT2}	DAC current output. Normally terminated at ground.
3	AGND	Analog Ground
4	DB3	Data Input Bit 3 (MSB)
5	DB2	Data Input Bit 2
6	DB1	Data Input Bit 1
7	DB0	Data Input Bit 0 (LSB)

PIN NO.	NAME	DESCRIPTION
8	$\overline{CS}$	Chip Select Input
9	$\overline{WR}$	Write Input
10	A0	Address Bus Input
11	A1	Address Bus Input
12	DGND	Digital Ground
13	$\overline{CLR}$	Clear Input
14	V_{DD}	+5 V Supply Input
15	V_{REF}	Reference Input
16	R_{FB}	DAC Feedback Resistor

ELECTRICAL CHARACTERISTICS

(V_{DD} = + 5 V, V_{REF} = +10 V unless otherwise noted)

Parameter	Symbol	25°C Min	25°C Typ	25°C Max	Tmin to Tmax Min	Tmin to Tmax Max	Units	Test Conditions/Comments
STATIC PERFORMANCE[1]								
Resolution (All Grades)	N	12			12		Bits	
Integral Non-Linearity (Relative Accuracy)	INL						LSB	Best Fit Straight Line Spec. (Max INL – Min INL) / 2
J, A, S				±1		±1		
K, B, T				±1/2		±1/2		
Differential Non-Linearity	DNL						LSB	Monotonicity
J, A, S				±2		±2		11 Bits Guaranteed
K, B, T				±1		±1		12 Bits Guaranteed
Gain Error								
J, A, S, K, B, T	GE			±12.3		±14.5	LSB	Using Internal R_{FB}
Gain Temperature Coefficient[2]	TC_{GE}					±2	ppm/°C	ΔGain/ΔTemperature
Power Supply Rejection Ratio	PSRR			±50		±100	ppm/%	$\lvert\Delta Gain/\Delta V_{DD}\rvert$ ΔV_{DD} = ± 5%
Output Leakage Current	I_{OUT}			±10		±200	nA	
DYNAMIC PERFORMANCE								R_L=100Ω, C_L=13pF
Current Settling Time[2]	t_S			2.0		2.0	µs	Full Scale Change to 1/2 LSB
AC Feedthrough at I_{OUT1}[2]	F_T			2.5		2.5	mV p-p	V_{REF} = 10kHz, 20 Vp-p, sinewave
REFERENCE INPUT								
Input Resistance	R_{IN}	5	10	20	5	20	kΩ	
DIGITAL INPUTS[3]								
Logical "1" Voltage	V_{IH}	3.0			3.0		V	
Logical "0" Voltage	V_{IL}			0.8		0.8	V	
Input Leakage Current	I_{LKG}			±1		±1	µA	
Input Capacitance[2]	C_{IN}			8		8	pF	
ANALOG OUTPUTS								
Output Capacitance[2]								
	C_{OUT1}			260		260	pF	DAC Inputs all 1's
	C_{OUT1}			100		100	pF	DAC Inputs all 0's
	C_{OUT2}			50		50	pF	DAC Inputs all 1's
	C_{OUT2}			210		210	pF	DAC Inputs all 0's
POWER SUPPLY								
Supply Voltage[5]	V_{DD}	+4.5		+5.5	+4.5	+5.5	V	
Supply Current	I_{DD}			2.5		2.5	mA	All digital inputs = 0 V or all = 5 V

ELECTRICAL CHARACTERISTICS (CONT'D)

Parameter	Symbol	25°C Min	25°C Typ	25°C Max	Tmin to Tmax Min	Tmin to Tmax Max	Units	Test Conditions/Comments
SWITCHING CHARACTERISTICS[2, 4]								
$\overline{WR}$ Pulse Width	t_{WR}	120			220		ns	
Address to $\overline{WR}$ Hold Time	t_{AWH}	50			65		ns	
$\overline{CS}$ to $\overline{WR}$ Hold Time	t_{CWH}	50			100		ns	
$\overline{CLR}$ Pulse Width	t_{CLR}	200			300		ns	
Byte Loading, $\overline{CS}$ to $\overline{WR}$ Setup	t_{CWS1}	60			130		ns	
Byte Loading, Address to $\overline{WR}$ Setup	t_{AWS1}	80			180		ns	
Byte Loading, $\overline{WR}$ to Data Setup	t_{DS}	50			65		ns	
Byte Loading, $\overline{WR}$ to Data Hold	t_{DH}	50			65		ns	
DAC Loading, $\overline{CS}$ to $\overline{WR}$ Setup	t_{CWS2}	60			150		ns	
DAC Loading, Address to $\overline{WR}$ Setup	t_{AWS2}	120			240		ns	

NOTES:

1 Full Scale Range (FSR) is 10V for unipolar mode.
2 Guaranteed but not production tested.
3 Digital input levels should not go below ground or exceed the positive supply voltage, otherwise damage may occur.
4 See timing diagram.
5 Specified values guarantee functionality. Refer to other parameters for accuracy.

Specifications are subject to change without notice

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C unless otherwise noted)[1, 2, 3]

V_{DD} to GND ..... +7 V
Digital Input Voltage to GND (2) . GND –0.5 to V_{DD} +0.5 V
I_{OUT1}, I_{OUT2} to GND ..... GND –0.5 to V_{DD} +0.5 V
V_{REF} to GND (2) ..... ±25 V
V_{RFB} to GND (2) ..... ±25 V
AGND to DGND ..... ±1 V
(Functionality Guaranteed ±0.5 V)

Storage Temperature ..... –65°C to +150°C

Lead Temperature (Soldering, 10 seconds) ..... +300°C

Package Power Dissipation Rating to 75°C
CDIP, PDIP, SOIC 700mW
Derates above 75°C ..... 10mW/°C

NOTES:

1 Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at or above this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.
2 Any input pin which can see a value outside the absolute maximum ratings should be protected by Schottky diode clamps (HP5082-2835) from input pin to the supplies.
3 GND refers to AGND and DGND.

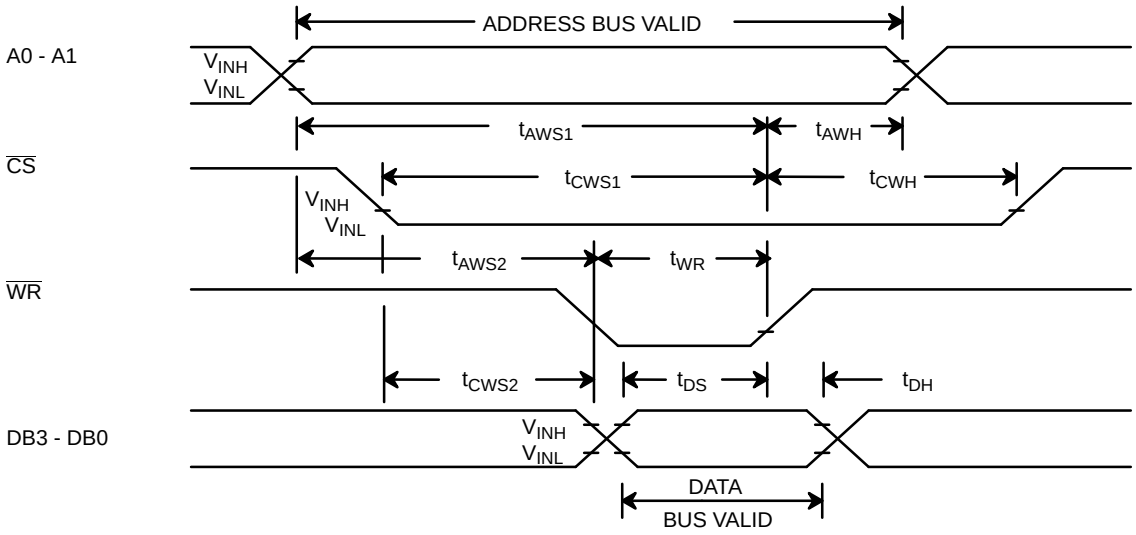


Figure 1. Timing Diagram

MP7542 Control Inputs					MP7542 Operation	
A_1	A_0	$\overline{CS}$	$\overline{WR}$	$\overline{CLR}$		
X	X	X	X	0	Resets DAC 12-bit register to code 0000 0000 0000	
X	X	1	1	1	No operation; device not selected	
0	0	↗	0	1	Load LOW byte data register on edges as shown	Load applicable data register with data at D_0 - D_3
0	0	0	↗	1		
0	1	↗	0	1	Load MIDDLE byte data register on edges as shown	
0	1	0	↗	1		
1	0	↗	0	1	Load HIGH byte data register on edges as shown	
1	0	0	↗	1		
1	1	0	0	1	Load 12-bit DAC register with data in LOW byte, MIDDLE byte, & HIGH byte data registers	
1	1	0	0	1		

NOTES
1. 1 indicates logic HIGH
2. 0 indicates logic LOW
3. X indicates don't care
4. ↗ indicates LOW to HIGH transition
5. MSB XXXX XXXX XXXX LSB
   high byte, middle byte, low byte
6. Although positive-going edge of either $\overline{CS}$ or $\overline{WR}$ will load data register, timing is optimized by using $\overline{WR}$ to latch data and using $\overline{CS}$ as a device enable.

Table 1. Truth Table

APPLICATION NOTES
Refer to Section 8 for Applications Information

Interface Logic Information

The MP7542 is designed to interface as a memory-mapped output device.

A typical system configuration is shown below. $\overline{CS}$ is the decoded device address, and is derived by decoding the 14 higher order address bits. A0 and A1 are the MP7542 operation address bits, and are decoded internally in the MP7542 to point to the desired loading operation (i.e. load high byte, middle byte, low byte or DAC register). *See Table 1.*

All data loading operations are identical to the write cycle of a RAM.

Additionally, the $\overline{CLR}$ input allows the MP7542 DAC register to be cleared asynchronously to 0000 0000 0000. When operating the MP7542 in a unipolar mode a CLEAR sets the DAC output to zero scale output. In the bipolar mode a CLEAR causes the DAC output to go to $-V_{REF}$.

In summary:

1. The MP7542 DAC register can be asynchronously cleared with the $\overline{CLR}$ input.
2. Each MP7542 requires only 4 bits of memory.
3. Any of the four basic loading operations (i.e. load low byte data register, middle byte data register, high byte data register or 12-bit DAC register) are accomplished by executing a memory WRITE operation to the applicable address location for the required DAC operation.

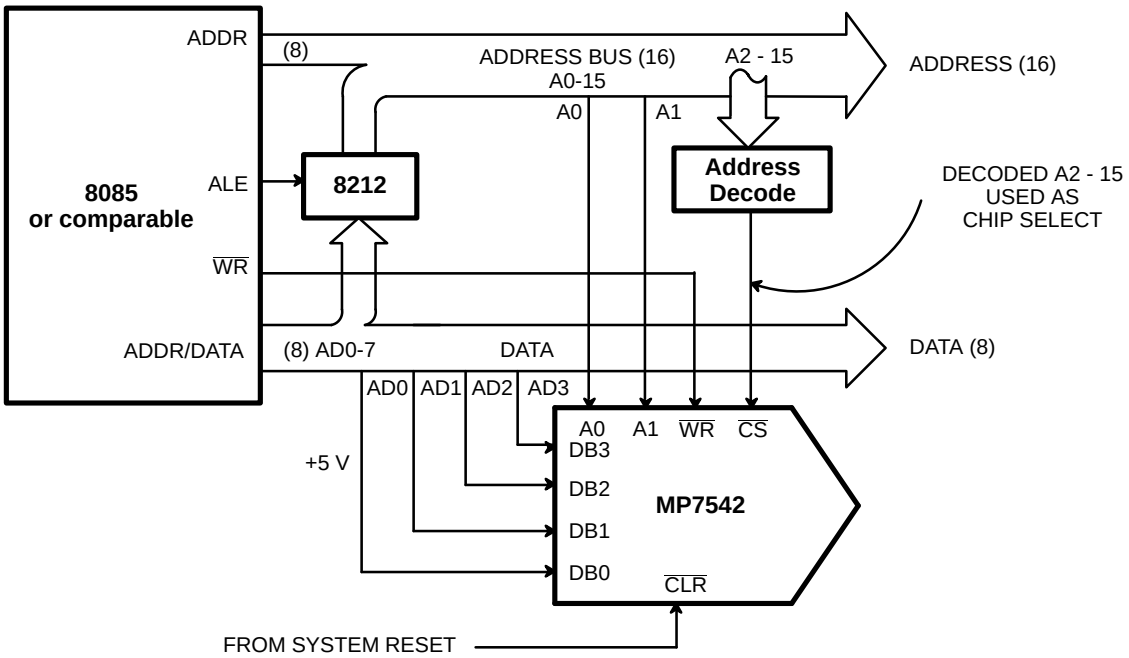
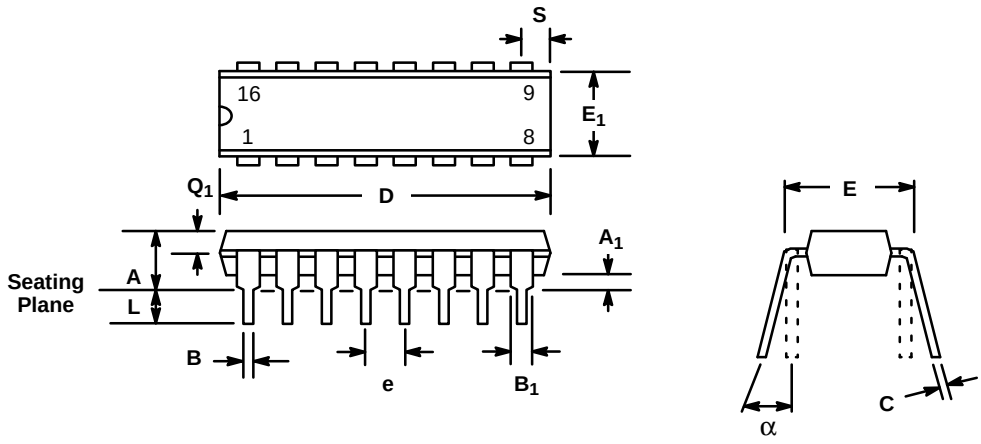


Figure 2. 8085/MP7542 Interface (Memory Mapped Output)

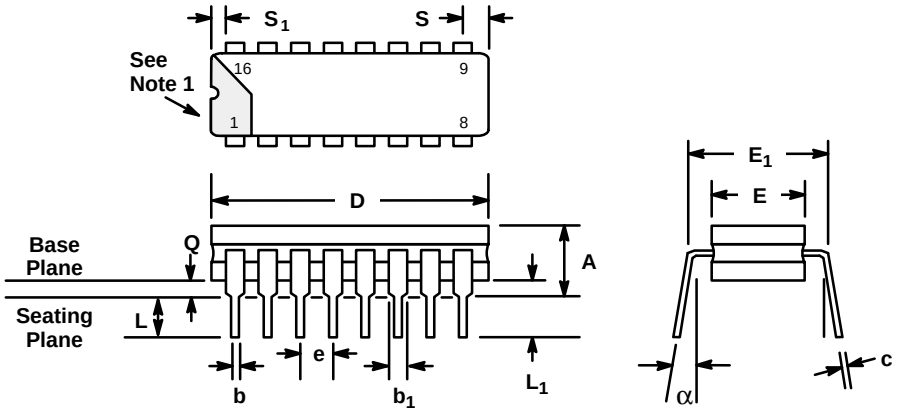
16 LEAD PLASTIC DUAL-IN-LINE
(300 MIL PDIP)
N16



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	—	0.200	—	5.08
A_1	0.015	—	0.38	—
B	0.014	0.023	0.356	0.584
B_1 (1)	0.038	0.065	0.965	1.65
C	0.008	0.015	0.203	0.381
D	0.745	0.785	18.92	19.94
E	0.295	0.325	7.49	8.26
E_1	0.220	0.310	5.59	7.87
e	0.100 BSC		2.54 BSC	
L	0.115	0.150	2.92	3.81
α	0°	15°	0°	15°
Q_1	0.055	0.070	1.40	1.78
S	0.020	0.080	0.51	2.03

Note: (1) The minimum limit for dimensions B1 may be 0.023” (0.58 mm) for all four corner leads only.

16 LEAD CERAMIC DUAL-IN-LINE
(300 MIL CDIP)
D16

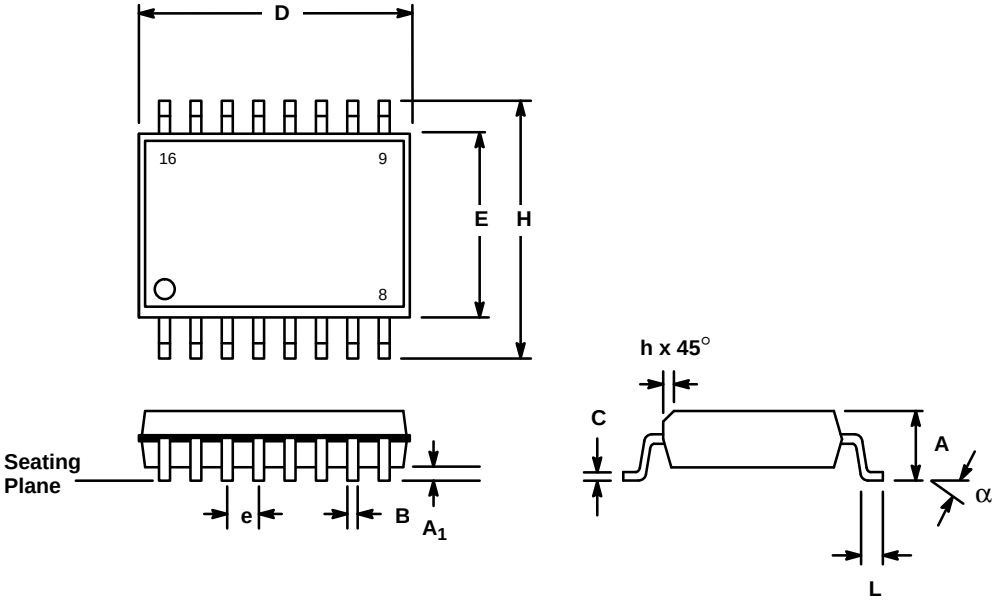


SYMBOL	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX	NOTES
A	—	0.200	—	5.08	—
b	0.014	0.023	0.356	0.584	—
b_1	0.038	0.065	0.965	1.65	2
c	0.008	0.015	0.203	0.381	—
D	—	0.840	—	21.34	4
E	0.220	0.310	5.59	7.87	4
E_1	0.290	0.320	7.37	8.13	7
e	0.100 BSC		2.54 BSC		5
L	0.125	0.200	3.18	5.08	—
L_1	0.150	—	3.81	—	—
Q	0.015	0.060	0.381	1.52	3
S	—	0.080	—	2.03	6
S_1	0.005	—	0.13	—	6
α	0°	15°	0°	15°	—

NOTES

1. Index area; a notch or a lead one identification mark is located adjacent to lead one and is within the shaded area shown.
2. The minimum limit for dimension b_1 may be 0.023 (0.58 mm) for all four corner leads only.
3. Dimension Q shall be measured from the seating plane to the base plane.
4. This dimension allows for off-center lid, meniscus and glass overrun.
5. The basic lead spacing is 0.100 inch (2.54 mm) between centerlines.
6. Applies to all four corners.
7. This is measured to outside of lead, not center.

16 LEAD SMALL OUTLINE
(300 MIL JEDEC SOIC)
S16



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.097	0.104	2.46	2.64
A_1	0.0050	0.0115	0.127	0.292
B	0.014	0.019	0.356	0.482
C	0.0091	0.0125	0.231	0.318
D	0.402	0.412	10.21	10.46
E	0.292	0.299	7.42	7.59
e	0.050 BSC		1.27 BSC	
H	0.400	0.410	10.16	10.41
h	0.010	0.016	0.254	0.406
L	0.016	0.035	0.406	0.889
α	0°	8°	0°	8°

Notes

Notes

NOTICE

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